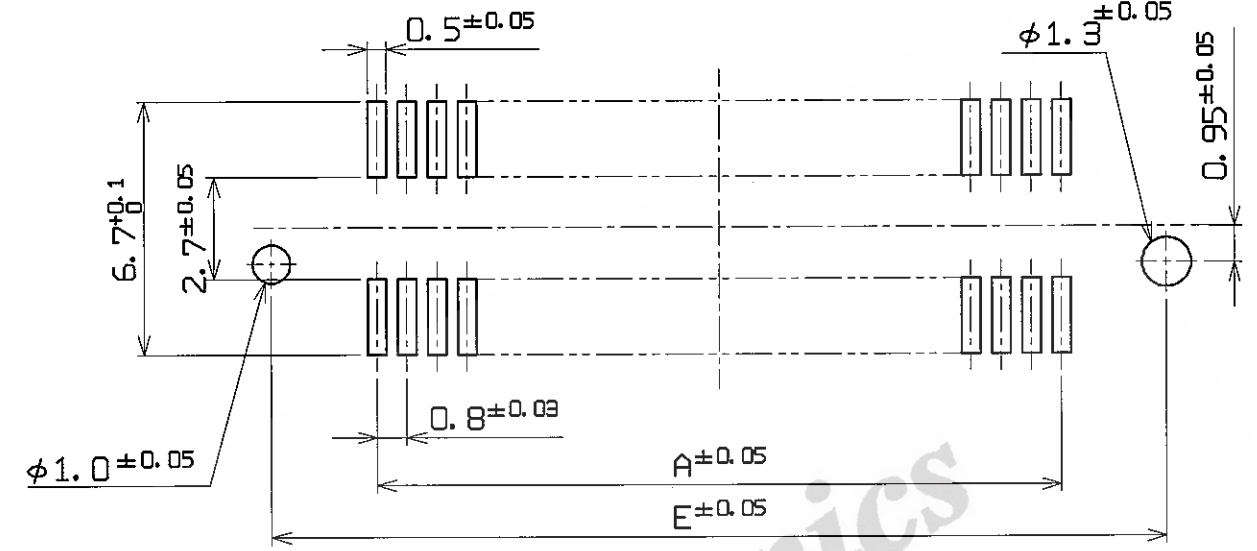
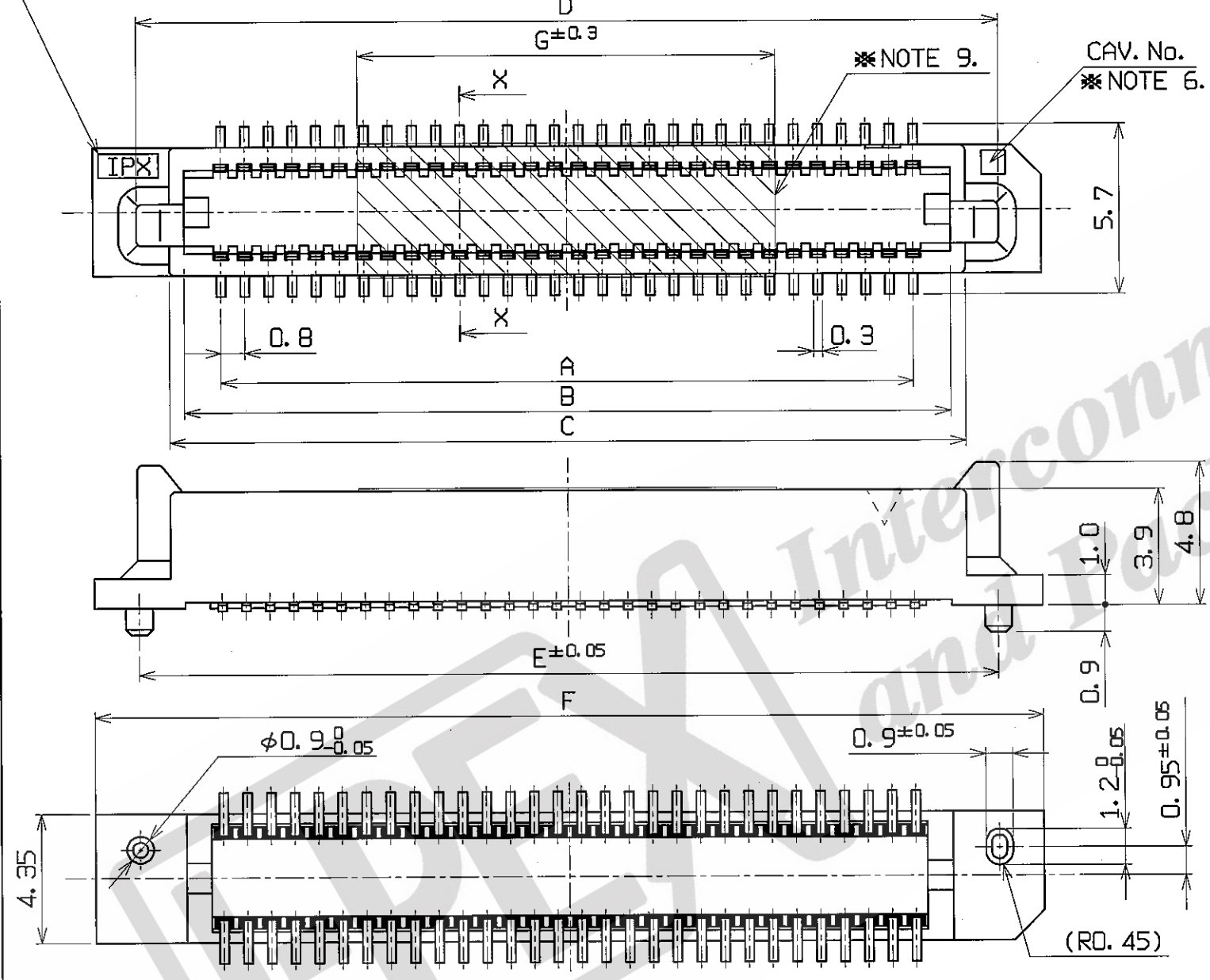


20001-100-##F	100	39.2	41.7	42.7	44.9	44.8	47.8	
20001-080-##F	80	31.2	33.7	34.7	36.9	36.8	39.8	
20001-060-##F	60	23.2	25.7	26.7	28.9	28.8	31.8	14.0
20001-050-##F	50	19.2	21.7	22.7	24.9	24.8	27.8	
20001-040-##F	40	15.2	17.7	18.7	20.9	20.8	23.8	
20001-030-##F	30	11.2	13.7	14.7	16.9	16.8	19.8	8.0
20001-020-##F	20	7.2	9.7	10.7	12.9	12.8	15.8	
20001-012-##F	12	4.0	6.5	7.5	9.7	9.6	12.6	6.0
PART No.	PIN	A	B	C	D	E	F	G

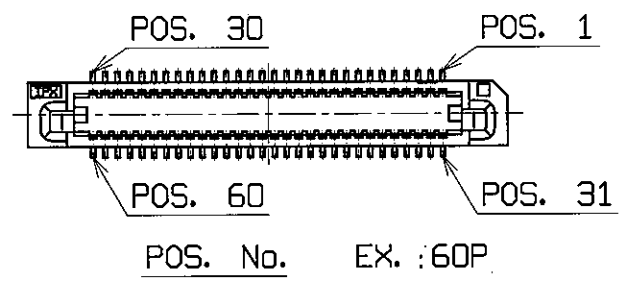
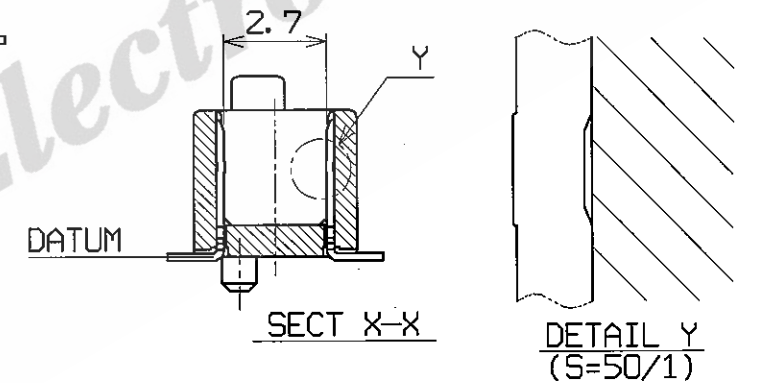
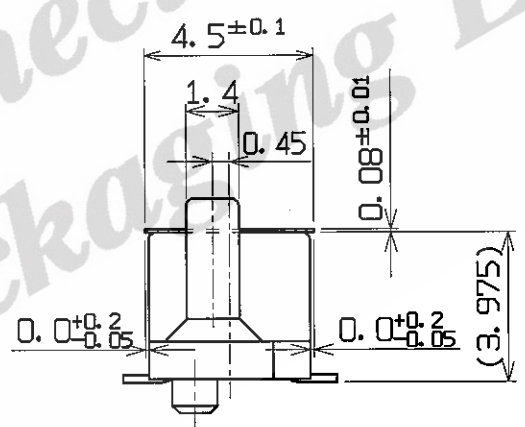
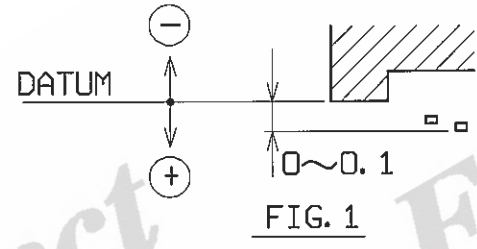
PART NO.	PIMPLE
20001-...-00F	NO
20001-...-01F	YES

☆EXAMPLE
 20001-060-##F : TUBE PACKAGE
 20001-060E-0#F : EMBOSS TAPING PACKAGE
 (ONLY 12~80 POS.)

LOGO MARK
 ※NOTE 8.



FOOTPRINT PATTERN



		DIM * H'		
PLUG	RECE	S(20004)	M(20005)	L(20006)
S(20001)		5.0	6.0	7.0
M(20002)		6.0	7.0	8.0
L(20003)		7.0	8.0	9.0

STACKING HEIGHT

NOTES
 1. MATERIAL/FINISH
 INSULATOR : GLASS REINFORCED LCP UL94V-0 (NATURAL)
 CONTACT : COPPER ALLOY UNDER PLATED NI 1.27μm MIN.
 CONTACT AREA : Au PLATED 0.5μm MIN.
 OTHERS : Au PLATED 0.03~0.07μm
 ADHESION TAPE : PI t=0.08±0.01

2. CURRENT RATING 0.5A
 3. WITHSTANDING VOLTAGE AC300V 1MINUTE
 4. INSULATION RESISTANCE DC250V 1,000MΩMIN.
 5. CONTACT RESISTANCE 40mΩMAX.
 ※6. CAV. No. (A, B, ...)
 7. 20001-...-0#F : SEE 300-454 OF THE PACKING STANDARD.
 20001-0+E-0#F : SEE 300-456 OF THE PACKING STANDARD.
 ※8. LOGO MARK INCLUDE THE INSC. BASE.
 ※9. ADHESION TAPE FOR EMBOSS TAPING PACKAGE.

DESIGN'D BY	M. TSUTSUMI	DATE	07/07/94	
CHK'D BY	Y. H	DATE	07/08/94	
APP'D BY	Y. FUKUDA	DATE	07/11/94	
REV.	ECN	BY	DATE	CHK
17	Z06404	K.T	Aug./21/06	J.R
REV. RECORD				
SERIES No.	2011			

I-PEX Interconnect and Packaging Electronics TOKYO, JAPAN

TOL. ±0.3, ±2'

TITLE VARISTACK PLUG(SHORT)

SCALE 5/1 UNIT mm DWG. No. 20001 SHEET 1/1 REV. 17